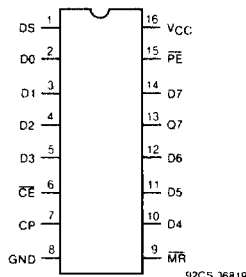


CD54/74HC166 CD54/74HCT166

File Number 1501

High-Speed CMOS Logic



TERMINAL ASSIGNMENT

8-Bit Parallel-In/Serial-Out Shift Register

Type Features:

- Buffered inputs
- Typical $f_{MAX} = 50 \text{ MHz}$ @ $V_{CC} = 5 \text{ V}$, $C_L = 15 \text{ pF}$, $T_A = 25^\circ \text{ C}$

The RCA-CD54/74HC166 and CD54/74HCT166 8-bit shift register is fabricated with silicon gate CMOS technology. It possesses the low power consumption of standard CMOS integrated circuits, and can operate at speeds comparable to the equivalent low power Schottky device.

The CD54/74HCT166 is functionally as well as pin compatible with the standard 54LS/74LS166.

The 166 is an 8-bit shift register that has fully synchronous serial or parallel data entry selected by an active LOW Parallel Enable (\overline{PE}) input. When the \overline{PE} is LOW one setup time before the LOW-to-HIGH clock transition, parallel data is entered into the register. When \overline{PE} is HIGH, data is entered into internal bit position Q_0 from Serial Data Input (DS), and the remaining bits are shifted one place to the right ($Q_0 \rightarrow Q_1 \rightarrow Q_2$, etc.) with each positive-going clock transition. For expansion of the register in parallel to serial converters, the Q_7 output is connected to the DS input of the succeeding stage.

The clock input is a gated OR structure which allows one input to be used as an active LOW Clock Enable (\overline{CE}) input. The pin assignment for the CP and \overline{CE} inputs is arbitrary and can be reversed for layout convenience. The LOW-to-HIGH transition of \overline{CE} input should only take place while the CP is HIGH for predictable operation.

A LOW on the Master Reset (\overline{MR}) input overrides all other inputs and clears the register asynchronously, forcing all bit positions to a LOW state.

The CD54HC166 and CD54HCT166 are supplied in 16-lead hermetic dual-in-line ceramic packages (F suffix). The CD74HC166 and CD74HCT166 are supplied in 16-lead dual-in-line plastic packages (E suffix) and in 16-lead dual-in-line surface mount plastic packages (M suffix). Both types are also available in chip form (H suffix).

Family Features:

- Fanout (Over Temperature Range):
Standard Outputs - 10 LSTTL Loads
Bus Driver Outputs - 15 LSTTL Loads
- Wide Operating Temperature Range:
CD74HC/HCT: -40 to $+85^\circ \text{ C}$
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- Alternate Source is Philips/Signetics
- CD54HC/CD74HC Types:
2 to 6 V Operation
High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} ; @ $V_{CC} = 5 \text{ V}$
- CD54HCT/CD74HCT Types:
4.5 to 5.5 V Operation
Direct LSTTL Input Logic Compatibility
 $V_{IL} = 0.8 \text{ V Max.}$, $V_{IH} = 2 \text{ V Min.}$
CMOS Input Compatibility
 $I_i \leq 1 \mu\text{A}$ @ V_{OL} , V_{OH}

CD54/74HC166 CD54/74HCT166

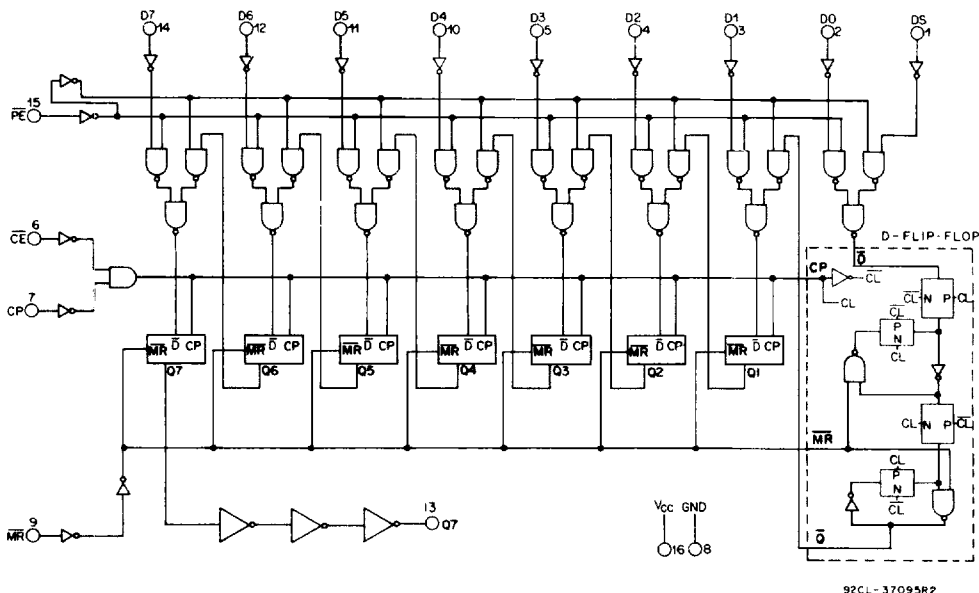


Fig. 1 - Logic diagram.

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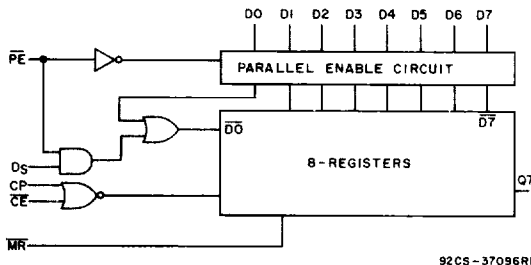


Fig. 2 - Functional diagram.

92CS-37096R1

TRUTH TABLE

Inputs					Parallel D0 D7	Internal Q States		Output Q7
Master Reset	Parallel Enable	Clock Enable	Clock	Serial		Q0 Q1		
L	X	X	X	X	X	L L	L	
H	X	L	L	X	X	Q00 Q10	Q0	
H	L	L	↗	X	a . . . h	a b	h	
H	H	L	↗	H	X	H Q0n	Q6n	
H	H	L	↗	L	X	L Q0n	Q6n	
H	X	H	↗	X	X	Q00 Q10	Q70	

H = high level (steady state).

L = low level (steady state).

X = irrelevant (any input, including transitions).

↗ = transition from low to high level.

a . . . h = the level of steady-state input at inputs D0 thru D7, respectively.

Q00, Q10, Q70 = the level of Q0, Q1, or Q7, respectively, before the indicated steady-state input conditions were established.

Q0n, Q6n = the level of Q0 or Q6, respectively, before the most recent 1 transition of the clock.

CD54/74HC166 CD54/74HCT166

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CD74HC166/CD54HC166										CD74HCT166/CD54HCT166										UNITS		
	TEST CONDITIONS			74HC/54HC TYPES			74HC TYPES		54HC TYPES			TEST CONDITIONS		74HCT/54HCT TYPES			74HCT TYPES		54HCT TYPES				
	V _i V	I _o mA	V _{cc} V	+25° C			-40/ +85° C		-55/ +125° C			V _i V	V _{cc} V	+25° C			-40/ +85° C		-55/ +125° C				
				Min	Typ	Max	Min	Max	Min	Max	Min			Max	Min	Max	Min	Max	Min	Max			
High-Level Input Voltage V _{ih}			2	1.5	—	—	1.5	—	1.5	—	—	4.5			2	—	—	2	—	2	—	V	
			4.5	3.15	—	—	3.15	—	3.15	—	—	to			5.5								
			6	4.2	—	—	4.2	—	4.2	—	—												
Low-Level Input Voltage V _{il}			2	—	—	0.5	—	0.5	—	0.5	—	4.5			—	—	0.8	—	0.8	—	0.8	V	
			4.5	—	—	1.35	—	1.35	—	1.35	—	to											
			6	—	—	1.8	—	1.8	—	1.8	—	5.5											
High-Level Output Voltage V _{oh}	V _{ih}	-0.02	2	1.9	—	—	1.9	—	1.9	—	V _{ih}											V	
or CMOS Loads	V _{ih}		4.5	4.4	—	—	4.4	—	4.4	—	4.4	or	4.5	4.4	—	—	4.4	—	4.4	—	4.4	—	V
	V _{ih}		6	5.9	—	—	5.9	—	5.9	—	5.9	V _{ih}											V
TTL Loads	V _{ih}										V _{ih}											V	
	or	-4	4.5	3.98	—	—	3.84	—	3.7	—	or	4.5	3.98	—	—	3.84	—	3.7	—	—	—	V	
	V _{ih}	-5.2	6	5.48	—	—	5.34	—	5.2	—	V _{ih}											V	
Low-Level Output Voltage V _{ol}	V _{ih}	0.02	2	—	—	0.1	—	0.1	—	0.1	V _{ih}											V	
or CMOS Loads	V _{ih}		4.5	—	—	0.1	—	0.1	—	0.1	—	or	4.5	—	—	0.1	—	0.1	—	0.1	—	0.1	V
	V _{ih}		6	—	—	0.1	—	0.1	—	0.1	—	V _{ih}											V
TTL Loads	V _{ih}										V _{ih}											V	
	or	4	4.5	—	—	0.26	—	0.33	—	0.4	or	4.5	—	—	0.26	—	0.33	—	0.4	—	0.4	V	
	V _{ih}	5.2	6	—	—	0.26	—	0.33	—	0.4	V _{ih}											V	
Input Leakage Current I _{ci}	V _{cc} or Gnd		6	—	—	±0.1	—	±1	—	±1	Any Voltage Between V _{cc} & Gnd	5.5	—	—	±0.1	—	±1	—	±1	—	±1	μA	
Quiescent Device Current I _{cc}	V _{cc} or Gnd	0	6	—	—	8	—	80	—	160	V _{cc} or Gnd	5.5	—	—	8	—	80	—	160	—	160	μA	
Additional Quiescent Device Current per input pin 1 unit load ΔI _{cc} *												4.5 to 5.5	—	100	360	—	450	—	490	—	490	μA	

*For dual-supply systems theoretical worst case (V_i = 2.4 V, V_{cc} = 5.5 V) specification is 1.8 mA.

HCT Input Loading Table

Input	Unit Loads*
DS, D0-D7	0.2
PE	0.35
CP, CE	0.5
MR	0.2

*Unit Load is ΔI_{cc} limit specified in Static Characteristic Chart, e.g., 360 μA max. @ 25° C.

CD54/74HC166 CD54/74HCT166

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE, (V _{CC}):	
(Voltages referenced to ground)	-0.5 to + 7 V
DC INPUT DIODE CURRENT, I _{IK} (FOR V _I < -0.5 V OR V _I > V _{CC} +0.5V)	±20mA
DC OUTPUT DIODE CURRENT, I _{OK} (FOR V _O < -0.5 V OR V _O > V _{CC} +0.5V)	±20mA
DC DRAIN CURRENT, PER OUTPUT (I _O) (FOR -0.5 V < V _O < V _{CC} + 0.5V)	±25mA
DC V _{CC} OR GROUND CURRENT (I _{CC})	±50mA
POWER DISSIPATION PER PACKAGE (P _D):	
For T _A = -40 to +60° C (PACKAGE TYPE E)	500 mW
For T _A = +60 to +85° C (PACKAGE TYPE E)	Derate Linearly at 8 mW/°C to 300 mW
For T _A = -55 to +100° C (PACKAGE TYPE F, H)	500 mW
For T _A = +100 to +125° C (PACKAGE TYPE F, H)	Derate Linearly at 8 mW/°C to 300 mW
For T _A = -40 to +70° C (PACKAGE TYPE M)	400 mW
For T _A = +70 to +125° C (PACKAGE TYPE M)	Derate Linearly at 6 mW/°C to 70 mW
OPERATING-TEMPERATURE RANGE (T _A):	
PACKAGE TYPE F, H	-55 to +125° C
PACKAGE TYPE E, M	-40 to +85° C
STORAGE TEMPERATURE (T _{STG})	-65 to +150° C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 ± 1/32 in. (1.59 ± 0.79 mm) from case for 10 s max.	+265° C
Unit inserted into a PC Board (min. thickness 1/16 in., 1.59 mm)	
with solder contacting lead tips only	+300° C

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply Voltage Range (For T _A = Full Package Temperature Range) V _{CC} :* CD54/74HC Types CD54/74HCT Types	2 4.5	6 5.5	V V
DC Input or Output Voltage V _{IN} , V _{OUT}	0	V _{CC}	V
Operating Temperature T _A : CD74 Types CD54 Types	-40 -55	+85 +125	°C °C
Input Rise and Fall Times, t _r , t _f at 2 V at 4.5 V at 6 V	0 0 0	1000 500 400	ns ns ns

SWITCHING CHARACTERISTICS (V_{CC} = 5 V, T_A = 25° C, input t_r, t_f = 6 ns)

CHARACTERISTIC	C _L pF	Typical		Units
		HC	HCT	
Propagation Delay- Clock to Q	t _{PLH} t _{PHL}	15	13 17	ns
Maximum Clock Frequency	f _{MAX}	15	50 50	MHz
Power Dissipation Capacitance*	C _{PD}	—	41 41	pF

*C_{PD} is used to determine the dynamic power consumption, per package.

$P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o)$ where: f_i=input frequency
f_o=output frequency
C_L=output load capacitance
V_{CC}=supply voltage

CD54/74HC166 CD54/74HCT166

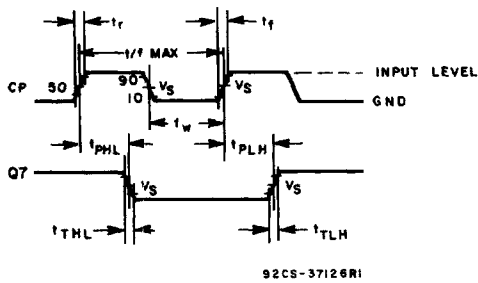
PRE-REQUISITE FOR SWITCHING FUNCTION

CHARACTERISTIC	TEST CONDITION	LIMITS												UNITS
		25° C				-40° C to +85° C				-55° C to +125° C				
		HC		HCT		74HC		74HCT		54HC		54HCT		
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Clock Frequency f_{max} Fig. 3	V _{CC} = 2	6	—	—	—	5	—	—	—	4	—	—	—	MHz
	V _{CC} = 4.5	30	—	25	—	25	—	20	—	20	—	16	—	
	V _{CC} = 6	35	—	—	—	29	—	—	—	23	—	—	—	
MR Pulse Width t_w Fig. 4	V _{CC} = 2	100	—	—	—	125	—	—	—	150	—	—	—	ns
	V _{CC} = 4.5	20	—	35	—	25	—	44	—	30	—	53	—	
	V _{CC} = 6	17	—	—	—	21	—	—	—	26	—	—	—	
Clock Pulse Width t_w Fig. 3	V _{CC} = 2	80	—	—	—	100	—	—	—	120	—	—	—	ns
	V _{CC} = 4.5	16	—	20	—	20	—	25	—	24	—	30	—	
	V _{CC} = 6	14	—	—	—	17	—	—	—	20	—	—	—	
Set-up Time t_{SU} Data and CE to Clock, Fig. 5, 6	V _{CC} = 2	80	—	—	—	100	—	—	—	120	—	—	—	ns
	V _{CC} = 4.5	16	—	16	—	20	—	20	—	24	—	24	—	
	V _{CC} = 6	14	—	—	—	17	—	—	—	20	—	—	—	
Hold Time t_H Data to Clock, Fig. 5	V _{CC} = 2	1	—	—	—	1	—	—	—	1	—	—	—	ns
	V _{CC} = 4.5	1	—	0	—	1	—	0	—	1	—	0	—	
	V _{CC} = 6	1	—	—	—	1	—	—	—	1	—	—	—	
Removal Time t_{REM} MR to Clock Fig. 4	V _{CC} = 2	0	—	—	—	0	—	—	—	0	—	—	—	ns
	V _{CC} = 4.5	0	—	0	—	0	—	0	—	0	—	0	—	
	V _{CC} = 6	0	—	—	—	0	—	—	—	0	—	—	—	
Set-up Time t_{SU} PE to CP Fig. 6	V _{CC} = 2	145	—	—	—	180	—	—	—	220	—	—	—	ns
	V _{CC} = 4.5	29	—	30	—	36	—	38	—	44	—	45	—	
	V _{CC} = 6	25	—	—	—	31	—	—	—	38	—	—	—	
Hold Time t_H PE to CP or CE Fig. 6	V _{CC} = 2	0	—	—	—	0	—	—	—	0	—	—	—	ns
	V _{CC} = 4.5	0	—	0	—	0	—	0	—	0	—	0	—	
	V _{CC} = 6	0	—	—	—	0	—	—	—	0	—	—	—	

SWITCHING CHARACTERISTICS (C_L = 50 pF, Input t_r = 6 ns)

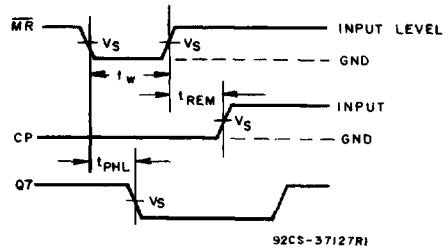
CHARACTERISTIC	TEST CONDITION	LIMITS												UNITS
		25° C				-40° C to +85° C				-55° C to +125° C				
		HC		HCT		74HC		74HCT		54HC		54HCT		
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Propagation Delay t_{PLH} Clock to Output t_{PHL} Fig. 3	V _{CC} = 2	—	160	—	—	—	200	—	—	—	240	—	—	ns
	V _{CC} = 4.5	—	32	—	40	—	40	—	50	—	48	—	60	
	V _{CC} = 6	—	27	—	—	—	34	—	—	—	41	—	—	
Output Transition Time t_{TLH} t_{THL} Fig. 3	V _{CC} = 2	—	75	—	—	—	95	—	—	—	110	—	—	ns
	V _{CC} = 4.5	—	15	—	15	—	19	—	19	—	22	—	22	
	V _{CC} = 6	—	13	—	—	—	16	—	—	—	19	—	—	
Propagation Delay t_{PHL} MR to Output Fig. 4	V _{CC} = 2	—	160	—	—	—	200	—	—	—	240	—	—	ns
	V _{CC} = 4.5	—	32	—	40	—	40	—	50	—	48	—	60	
	V _{CC} = 6	—	27	—	—	—	34	—	—	—	41	—	—	
Input Capacitance C_i			10		10		10		10		10		10	pF

CD54/74HC166 CD54/74HCT166



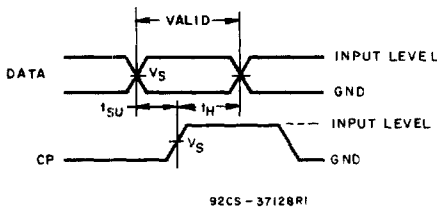
	54/74HC	54/74HCT
INPUT LEVEL	V_{CC}	3.0 V
V_S	50% V_{CC}	1.3 V

Fig. 3 - Clock pre-requisite times and propagation and output transition times.



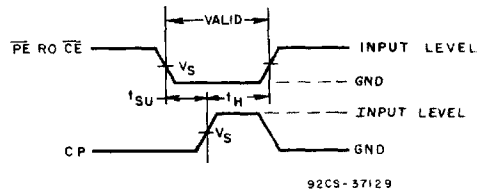
	54/74HC	54/74HCT
INPUT LEVEL	V_{CC}	3.0 V
V_S	50% V_{CC}	1.3 V

Fig. 4 - Master reset pre-requisite times and propagation delays.



	54/74HC	54/74HCT
INPUT LEVEL	V_{CC}	3.0 V
V_S	50% V_{CC}	1.3 V

Fig. 5 - Data pre-requisite times.



	54/74 HC	54/74 HCT
INPUT LEVEL	V_{CC}	3.0 V
V_S	50% V_{CC}	1.3 V

Fig. 6 - Parallel enable or clock enable pre-requisite times.